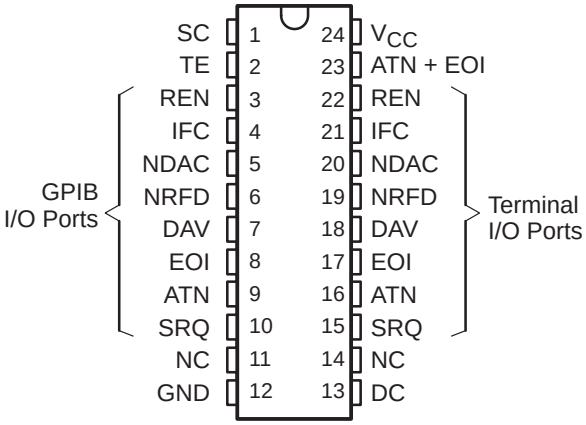
SLLS022C – JUNE 1986 – REVISED MAY 1998

- **8-Channel Bidirectional Transceiver**
- **Designed to Implement Control Bus Interface**
- **Designed for Multiple-Controller Systems**
- **High-Speed Advanced Low-Power Schottky Circuitry**
- **Low-Power Dissipation . . . 46 mW Max Per Channel**
- **Fast Propagation Times . . . 20 ns Max**
- **High-Impedance pnp Inputs**
- **Receiver Hysteresis . . . 650 mV Typ**
- **Bus-Terminating Resistors Provided on Driver Outputs**
- **No Loading of Bus When Device Is Powered Down (V_{CC} = 0)**
- **Power-Up/Power-Down Protection (Glitch Free)**

DW PACKAGE
(TOP VIEW)



NC – No internal connection

NOT RECOMMENDED FOR NEW DESIGNS

description

The SN75ALS164 eight-channel general-purpose interface bus transceiver is a monolithic, high-speed, advanced low-power Schottky device designed to meet the requirements of IEEE Standard 488-1978. Each transceiver is designed to provide the bus-management and data-transfer signals between operating units of a multiple-controller instrumentation system. When combined with the SN75ALS160 octal bus transceiver, the SN75ALS164 provides the complete 16-wire interface for the IEEE 488 bus.

The SN75ALS164 features eight driver-receiver pairs connected in a front-to-back configuration to form input/output (I/O) ports at both the bus and terminal sides. All outputs are disabled (at the high-impedance state) during V_{CC} power-up and power-down transitions for glitch-free operation. The direction of data flow through these driver-receiver pairs is determined by the DC, TE, and SC enable signals. The SN75ALS164 is identical to the SN75ALS162 with the addition of an OR gate to help simplify board layouts in several popular applications. The ATN and EOI signals are ORed to provide the ATN + EOI output, which is a standard totem-pole output.

The driver outputs (GPIB I/O ports) feature active bus-terminating resistor circuits designed to provide a high impedance to the bus when supply voltage V_{CC} is 0. The drivers are designed to handle loads up to 48 mA of sink current. Each receiver features pnp transistor inputs for high input impedance and hysteresis of 400 mV minimum for increased noise immunity. All receivers have 3-state outputs that present a high impedance to the terminal when disabled.

The SN75ALS164 is characterized for operation from 0°C to 70°C.

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

Copyright © 1998, Texas Instruments Incorporated

CHANNEL IDENTIFICATION TABLE

NAME	IDENTITY	CLASS
DC TE SC	Direction-Control Talk-Enable System Control	Control
ATN SRQ REN IFC EOI	Attention Service Request Remote Enable Interface Clear End or Identity	Bus Management
ATN+EOI	ATN Logical or EOI	Logic
DAV NDAC NRFD	Data Valid No Data Accepted Not Ready for Data	Data Transfer

Function Tables

RECEIVE/TRANSMIT FUNCTION TABLE

CONTROLS				BUS-MANAGEMENT CHANNELS					DATA-TRANSFER CHANNELS		
SC	DC	TE	ATN†	ATN† (controlled by DC)	SRQ (controlled by DC)	REN (controlled by SC)	IFC (controlled by SC)	EOI	DAV (controlled by TE)	NDAC (controlled by TE)	NRFD (controlled by TE)
	H	H	H	R	T			T	T	R	R
	H	H	L					R			
	L	L	H	T	R			R	R	T	T
	L	L	L					T			
	H	L	X	R	T			R	R	T	T
	L	H	X	T	R			T	T	R	R
H						T	T				
L						R	R				

H = high level, L = low level, R = receive, T = transmit, X = irrelevant

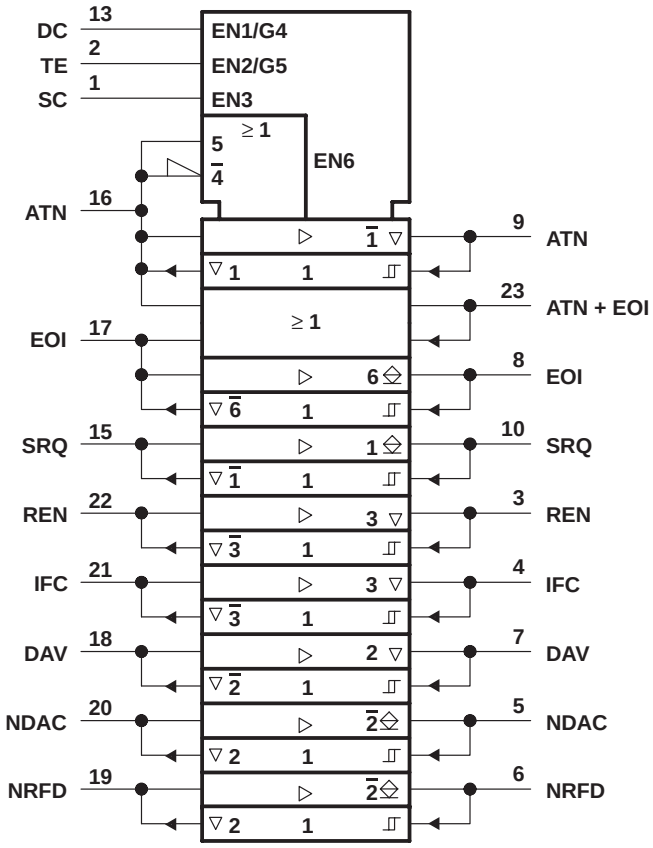
Direction of data transmission is from the terminal side to the bus side, and the direction of data receiving is from the bus side to the terminal side. Data transfer is noninverting in both directions.

† ATN is a normal transceiver channel that functions additionally as an internal direction control or talk enable for EOI when the DC and TE inputs are in the same state. When DC and TE are in opposite states, the ATN channel functions as an independent transceiver only.

ATN + EOI FUNCTION TABLE

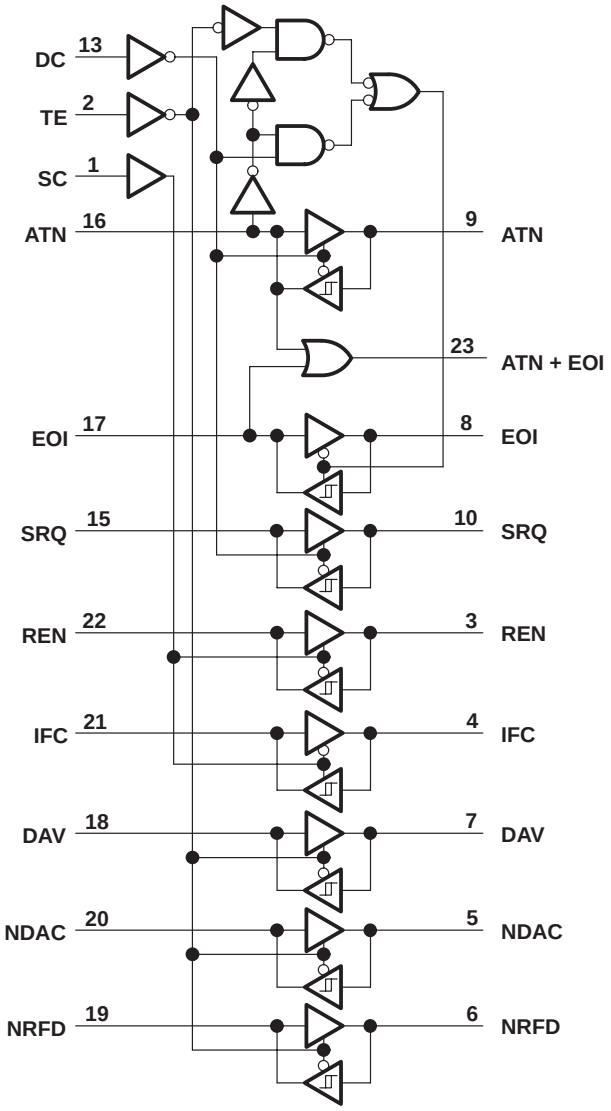
INPUTS		OUTPUT ATN + EOI
ATN	EOI	
H	X	H
X	H	H
L	L	L

logic symbol†



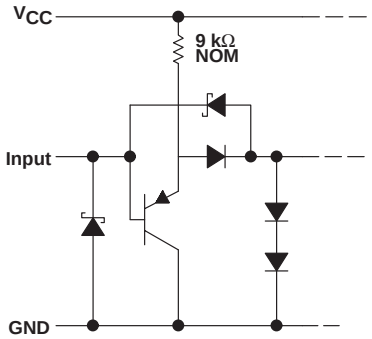
† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.
▽ Designates 3-state outputs
⏀ Designates passive-pullup outputs

logic diagram (positive logic)

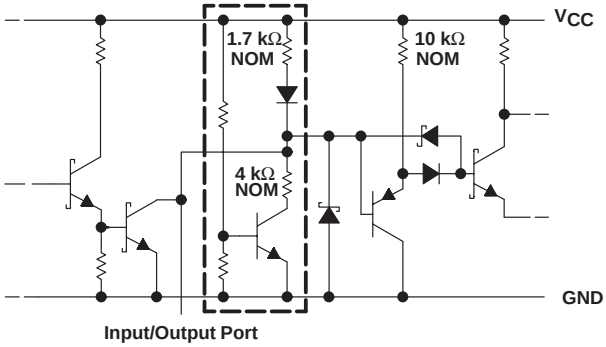


schematics of inputs and outputs

EQUIVALENT OF ALL CONTROL INPUTS

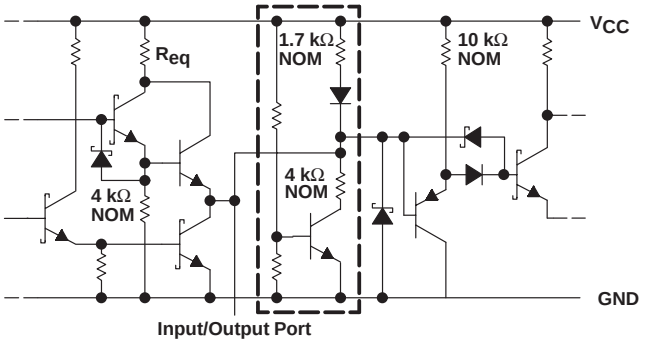


TYPICAL OF SRQ, NDAC, AND NRFD GPIB I/O PORT



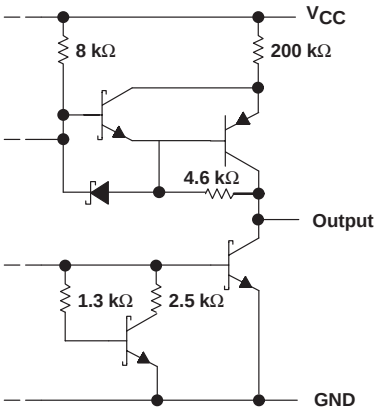
Circuit inside dashed lines is on the driver outputs only.

TYPICAL OF ALL I/O PORTS EXCEPT SRQ, NDAC, AND NRFD GPIB I/O PORTS



Driver output R_{eq} = 30 Ω NOM
Receiver output R_{eq} = 110 Ω NOM
Circuit inside dashed lines is on the driver outputs only.

ATN + EOI OUTPUT



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V_{CC} (see Note 1)	7 V
Input voltage	5.5 V
Low-level driver output current	100 mA
Package thermal impedance, θ_{JA} (see Note 2)	81°C/W
Storage temperature range, T_{stg}	– 65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from the case for 10 seconds	260°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltage values are with respect to network ground terminal.
2. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions

		MIN	NOM	MAX	UNIT
Supply voltage, V_{CC}		4.75	5	5.25	V
High-level input voltage, V_{IH}		2			V
Low-level input voltage, V_{IL}				0.8	V
High-level output current, I_{OH}	Bus ports with 3-state outputs			– 5.2	mA
	Terminal ports			– 800	µA
	ATN + EOI			– 400	
Low-level output current, I_{OL}	Bus ports			48	mA
	Terminal ports			16	
	ATN + EOI			4	
Operating free-air temperature, T_A		0		70	°C

electrical characteristics over recommended supply-voltage and operating free-air temperature ranges (unless otherwise noted)

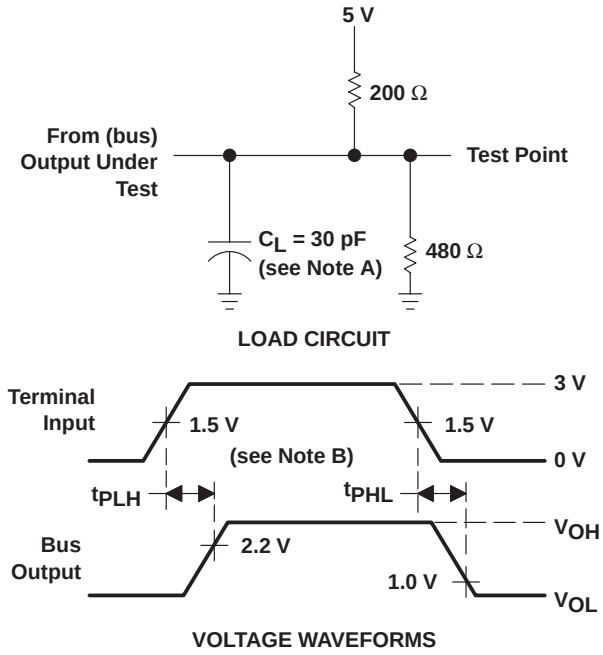
PARAMETER			TEST CONDITIONS		MIN	TYP†	MAX	UNIT
V_{IK}	Input clamp voltage		I_I = –18 mA			– 0.8	–1.5	V
V_{hys}	Hysteresis ($V_{T+} – V_{T–}$)	Bus			0.4	0.65		V
V_{OH}‡	High-level output voltage	Terminal	I_{OH} = – 800 µA		2.7	3.5		V
		Bus	I_{OH} = – 5.2 mA		2.5	3.3		
		ATN+EOI	I_{OH} = – 400 µA		2.7			
V_{OL}	Low-level output voltage	Terminal	I_{OL} = 16 mA			0.3	0.5	V
		Bus	I_{OL} = 48 mA			0.35	0.5	
		ATN+EOI	I_{OL} = 4 mA				0.4	
I_I	Input current at maximum input voltage	Terminal§	V_I = 5.5 V			0.2	100	µA
		ATN, EOI	V_I = 5.5 V				200	
I_{IH}	High-level input current	Terminal control	V_I = 2.7 V			0.1	20	µA
		ATN, EOI	V_I = 2.7 V				40	
I_{IL}	Low-level input current	Terminal control	V_I = 0.5 V			–10	–100	µA
		ATN, EOI	V_I = 0.5 V				– 500	
$V_{I/O(bus)}$	Voltage at bus port		Driver disabled	$I_{I(bus)}$ = 0	2.5	3.0	3.7	V
				$I_{I(bus)}$ = –12 mA			–1.5	
$I_{I/O(bus)}$	Current into bus port	Power on	Driver disabled	$V_{I(bus)}$ = –1.5 V to 0.4 V	–1.3			mA
				$V_{I(bus)}$ = 0.4 V to 2.5 V	0		– 3.2	
				$V_{I(bus)}$ = 2.5 V to 3.7 V			+ 2.5 – 3.2	
				$V_{I(bus)}$ = 3.7 V to 5 V	0		2.5	
				$V_{I(bus)}$ = 5 V to 5.5 V	0.7		2.5	
		Power off	V_{CC} = 0,	$V_{I(bus)}$ = 0 to 2.5 V			– 40	µA
I_{OS}	Short-circuit output current	Terminal			–15	– 35	– 75	mA
		Bus			– 25	– 50	–125	
		ATN + EOI			–10		–100	
I_{CC}	Supply current		No load,	TE, DC, and SC low		55	75	mA
$C_{I/O(bus)}$	Bus-port capacitance		V_{CC} = 0 to 5 V,	$V_{I/O}$ = 0 to 2 V, f = 1 MHz		30		pF

† All typical values are at V_{CC} = 5 V, T_A = 25°C.
‡ V_{OH} applies for 3-state outputs only.
§ Except ATN and EOI terminals.

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V

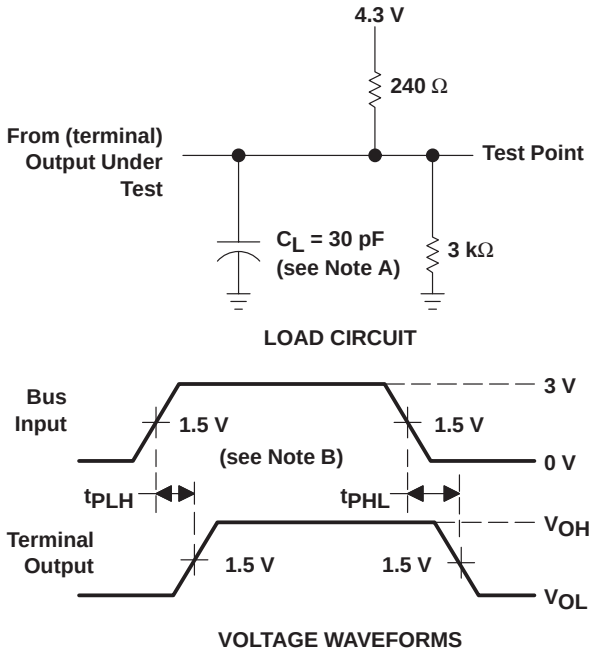
PARAMETER		FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{PLH}	Propagation delay time, low-to-high-level output	Terminal	Bus	C_L = 30 pF, See Figure 1		10	20	ns
t_{PHL}	Propagation delay time, high-to-low-level output					12	20	
t_{PLH}	Propagation delay time, low-to-high-level output	Bus	Terminal	C_L = 30 pF, See Figure 2		5	10	ns
t_{PHL}	Propagation delay time, high-to-low-level output					7	14	
t_{PLH}	Propagation delay time, low-to-high-level output	Terminal ATN or Terminal EOI	ATN+EOI	C_L = 15 pF, See Figure 3		3.5	10	ns
t_{PHL}	Propagation delay time, high-to-low-level output	Terminal ATN or Terminal EOI	ATN+EOI	C_L = 15 pF, See Figure 3		7	15	ns
t_{PZH}	Output enable time to high level	TE, DC, or SC	Bus (ATN, EOI, REN, IFC, and DAV)	C_L = 15 pF, See Figure 4			30	ns
t_{PHZ}	Output disable time from high level						20	
t_{PZL}	Output enable time to low level						45	
t_{PLZ}	Output disable time from low level						20	
t_{PZH}	Output enable time to high level	TE, DC, or SC	Terminal	C_L = 15 pF, See Figure 5			30	ns
t_{PHZ}	Output disable time from high level						25	
t_{PZL}	Output enable time to low level						30	
t_{PLZ}	Output disable time from low level						25	

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.
B. The input pulse is supplied by a generator having the following characteristics: PRR ≤ 1 MHz, 50% duty cycle, t_r ≤ 6 ns, t_f ≤ 6 ns, Z_O = 50 Ω.

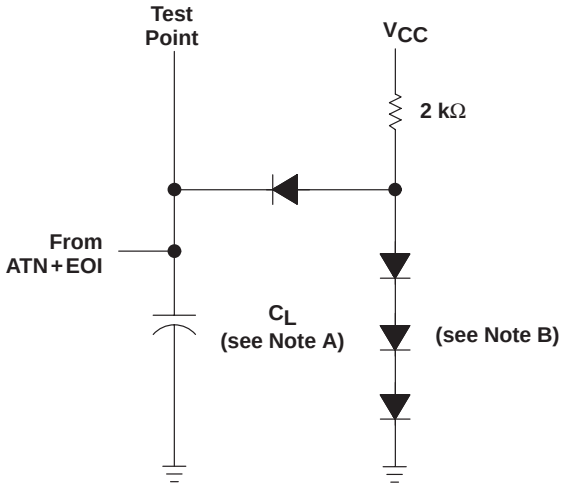
Figure 1. Terminal-to-Bus Load Circuit and Voltage Waveforms



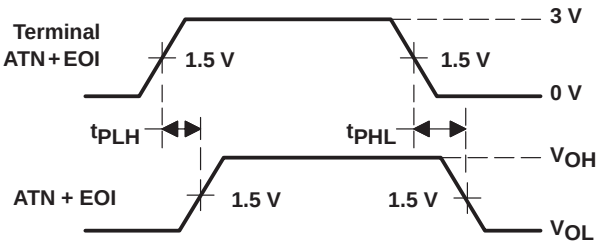
NOTES: A. C_L includes probe and jig capacitance.
B. The input pulse is supplied by a generator having the following characteristics: PRR ≤ 1 MHz, 50% duty cycle, t_r ≤ 6 ns, t_f ≤ 6 ns, Z_O = 50 Ω.

Figure 2. Bus-to-Terminal Load Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION



LOAD CIRCUIT

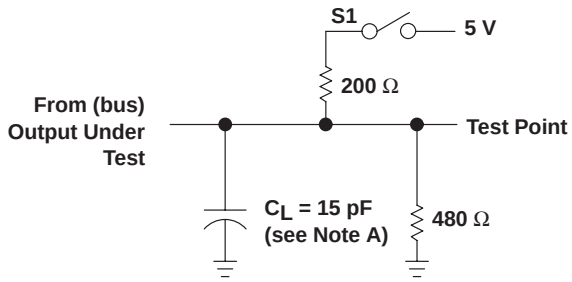


VOLTAGE WAVEFORMS

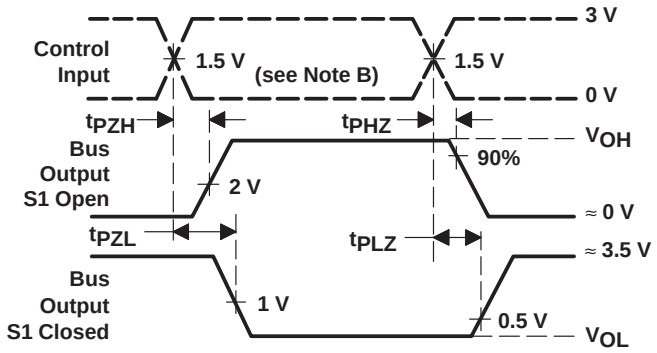
NOTES: A. C_L includes probe and jig capacitance.
B. All diodes are 1N916 or 1N3064

Figure 3. ATN + EOI Load Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION



LOAD CIRCUIT

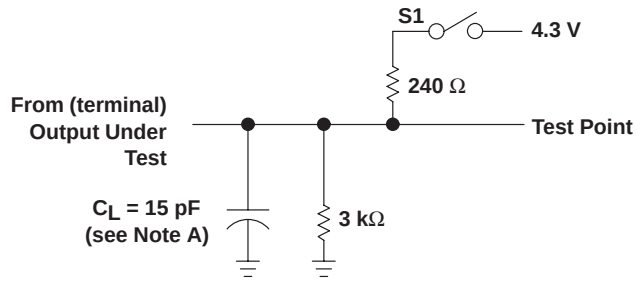


VOLTAGE WAVEFORMS

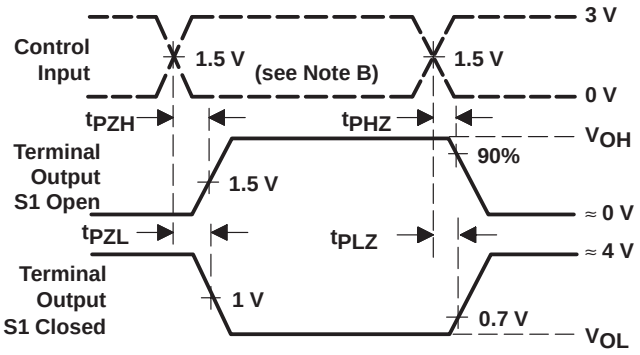
NOTES: A. C_L includes probe and jig capacitance.
B. The input pulse is supplied by a generator having the following characteristics: PRR ≤ 1 MHz, 50% duty cycle, t_r ≤ 6 ns, t_f ≤ 6 ns, Z_O = 50 Ω.

Figure 4. Bus Load Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION



LOAD CIRCUIT



VOLTAGE WAVEFORMS

NOTES: A. C_L includes probe and jig capacitance.
B. The input pulse is supplied by a generator having the following characteristics: PRR ≤ 1 MHz, 50% duty cycle, t_r ≤ 6 ns, t_f ≤ 6 ns, Z_O = 50 Ω.

Figure 5. Terminal Load Circuit and Voltage Waveforms

TYPICAL CHARACTERISTICS

TERMINAL HIGH-LEVEL OUTPUT VOLTAGE vs HIGH-LEVEL OUTPUT CURRENT

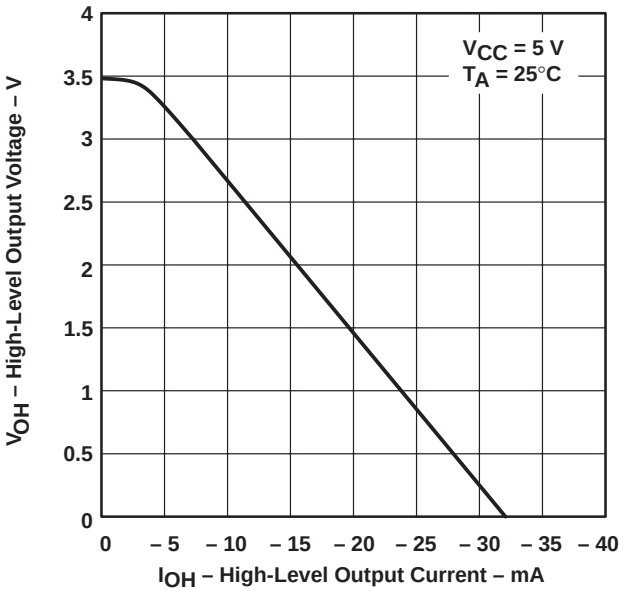


Figure 6

TERMINAL LOW-LEVEL OUTPUT VOLTAGE vs LOW-LEVEL OUTPUT CURRENT

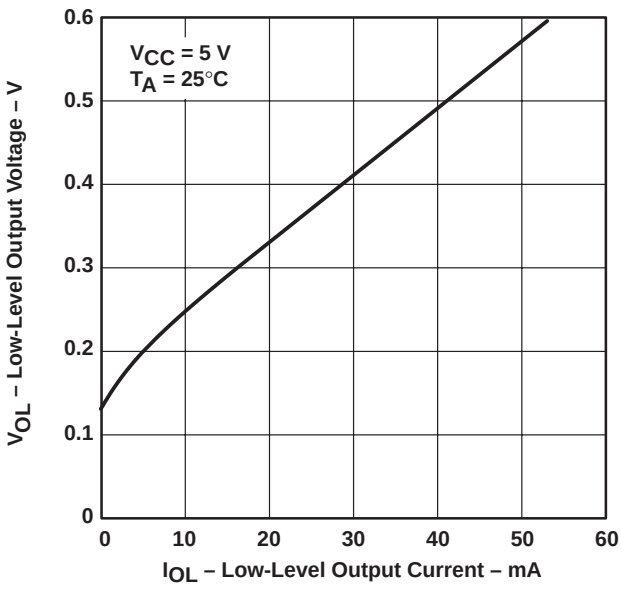


Figure 7

TERMINAL OUTPUT VOLTAGE vs BUS INPUT VOLTAGE

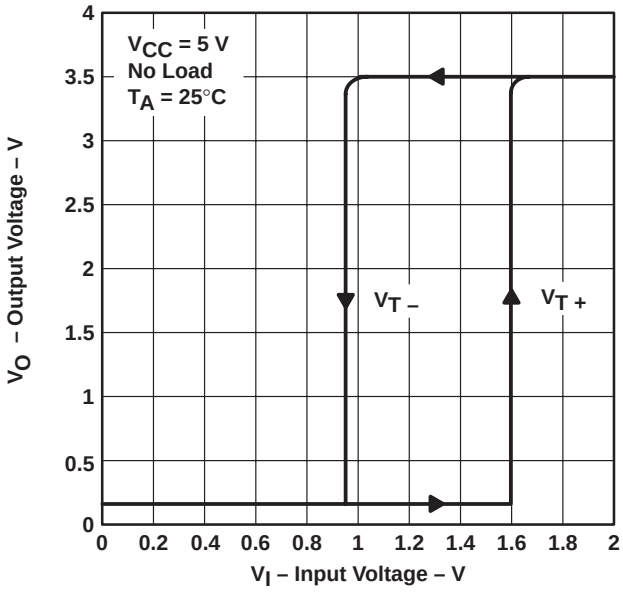


Figure 8

TYPICAL CHARACTERISTICS

BUS HIGH-LEVEL OUTPUT VOLTAGE vs BUS HIGH-LEVEL OUTPUT CURRENT

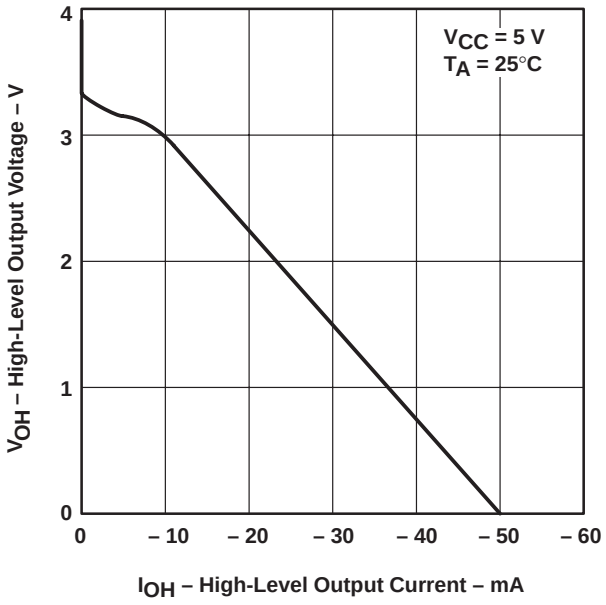


Figure 9

BUS LOW-LEVEL OUTPUT VOLTAGE vs BUS LOW-LEVEL OUTPUT CURRENT

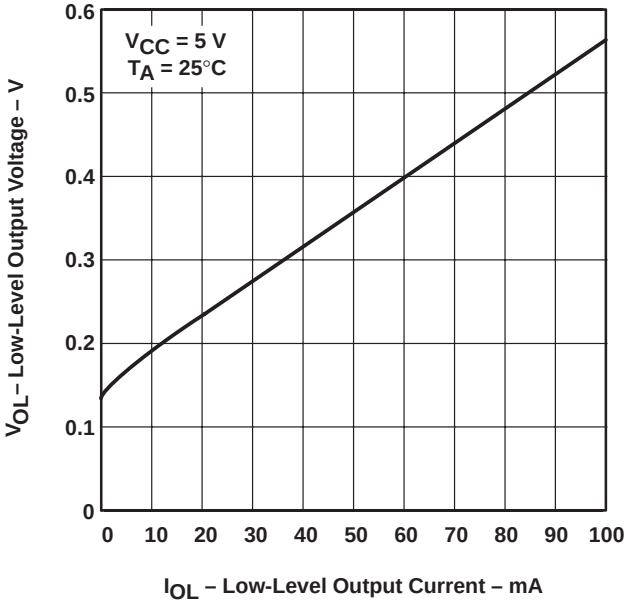


Figure 10

BUS OUTPUT VOLTAGE vs TERMINAL INPUT VOLTAGE

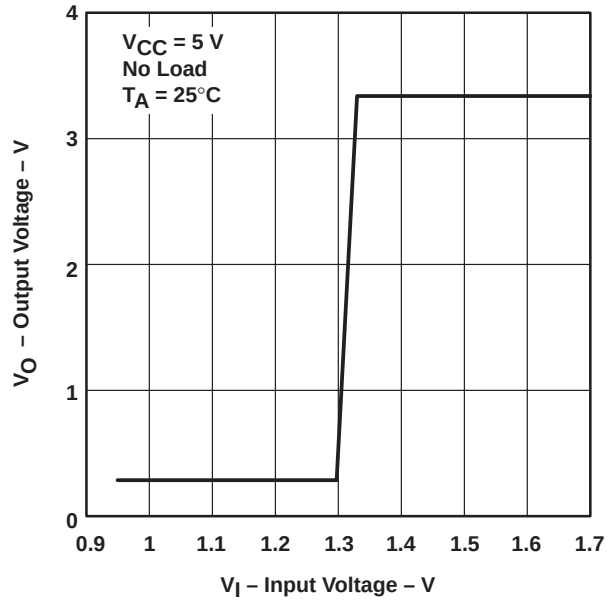


Figure 11

BUS CURRENT vs BUS VOLTAGE

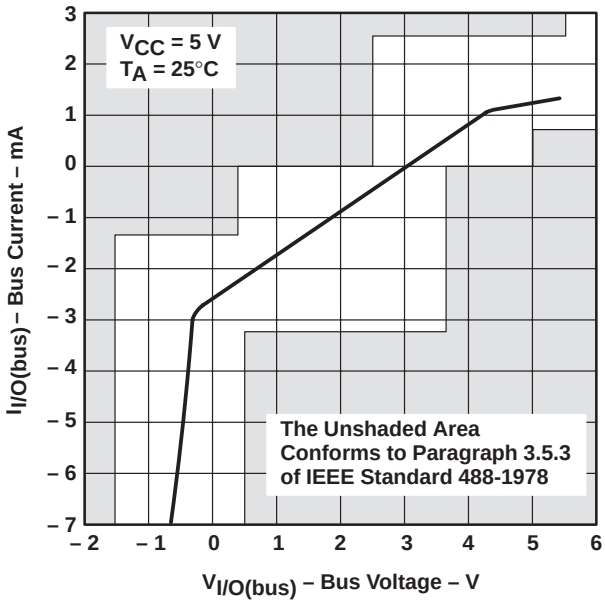


Figure 12

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/ Ball Finish	MSL Peak Temp (3)	Samples (Requires Login)
SN75ALS164DW	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
SN75ALS164DWR	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
SN75ALS164DWRE4	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
SN75ALS164DWRG4	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
SN75ALS164N	OBSOLETE	PDIP	N	22		TBD	Call TI	Call TI	Samples Not Available

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

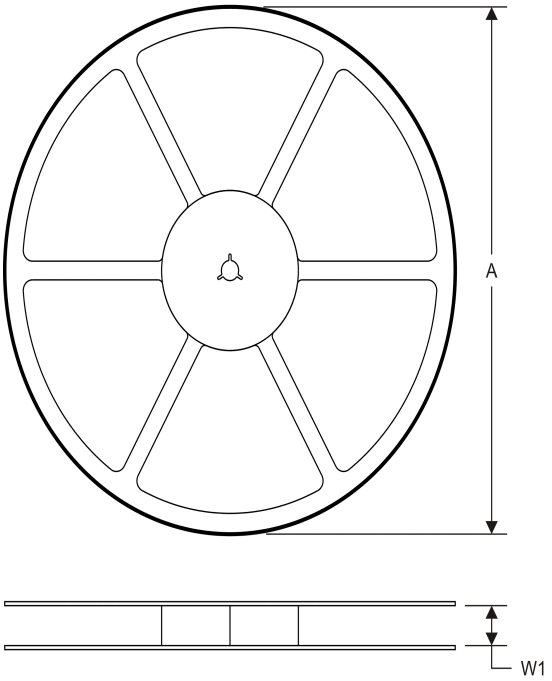
(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

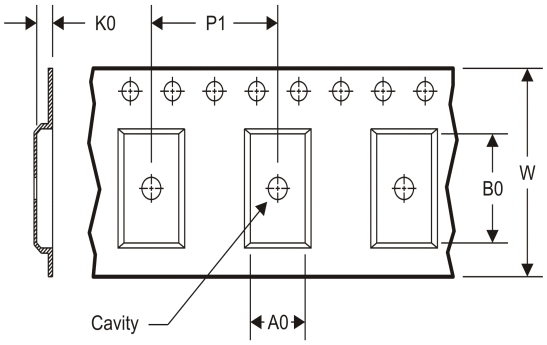
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION

REEL DIMENSIONS



TAPE DIMENSIONS



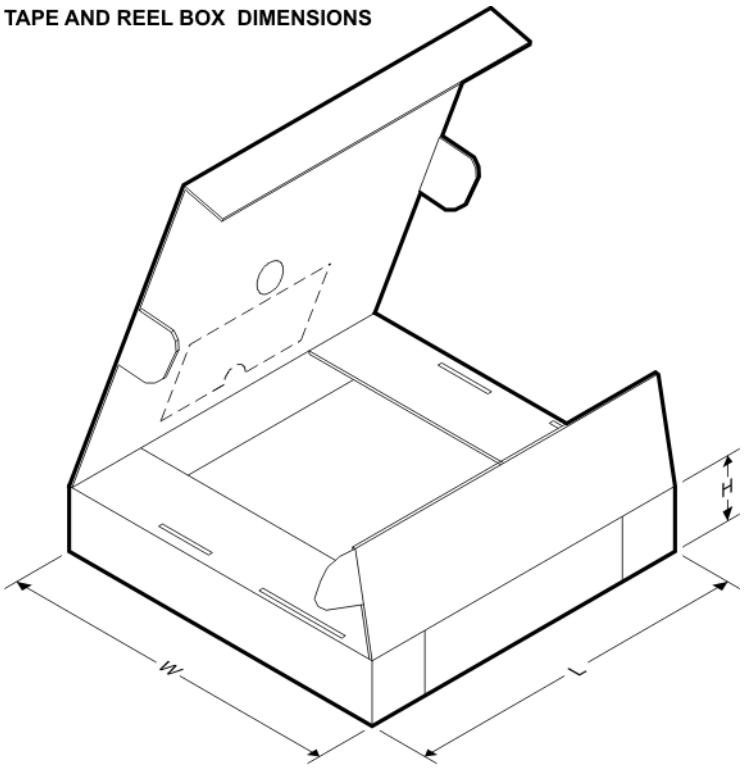
A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN75ALS164DWR	SOIC	DW	24	2000	330.0	24.4	10.75	15.7	2.7	12.0	24.0	Q1

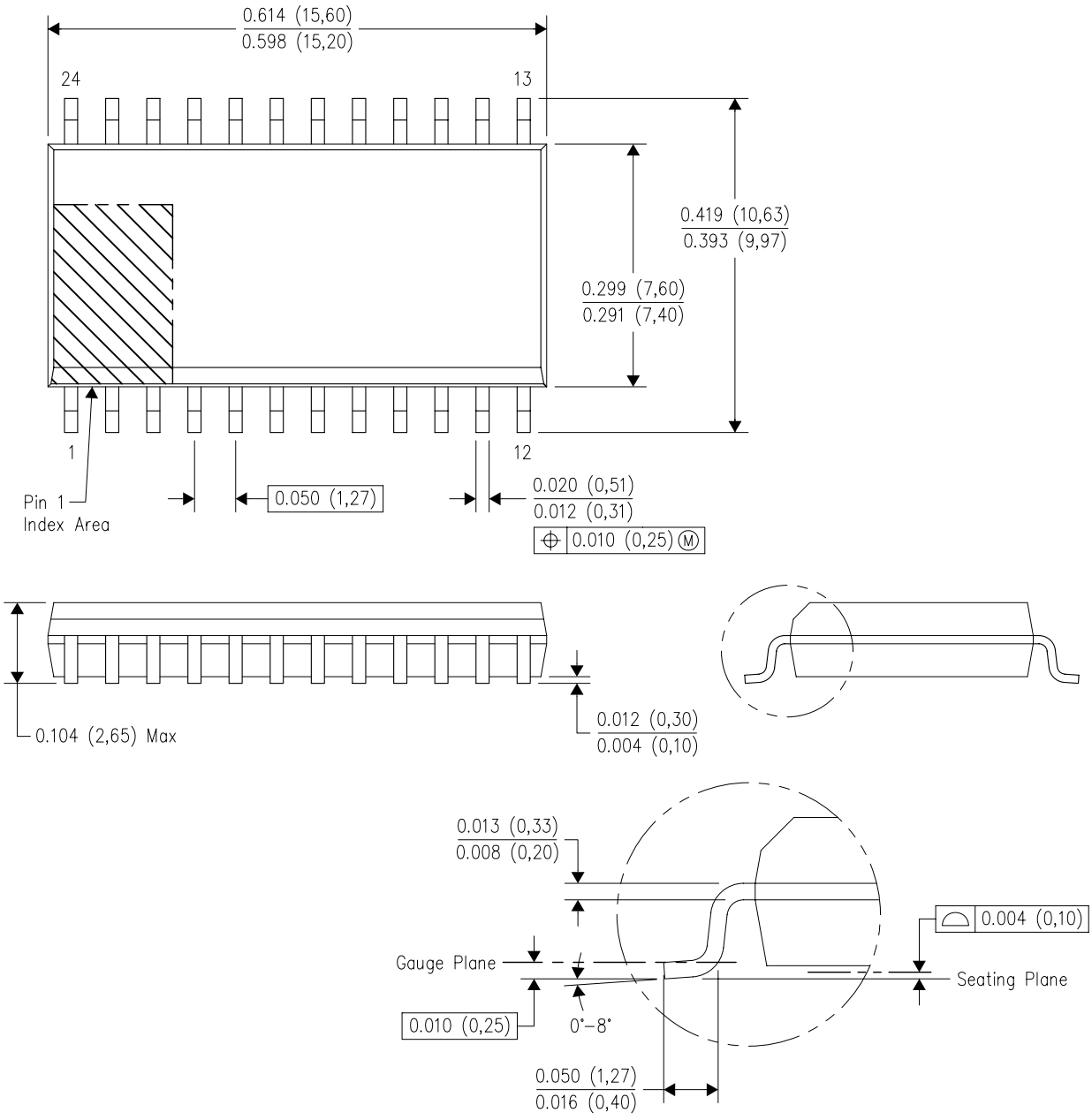
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN75ALS164DWR	SOIC	DW	24	2000	367.0	367.0	45.0

DW (R–PDSO–G24) PLASTIC SMALL OUTLINE



NOTES:
A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M–1994.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
D. Falls within JEDEC MS–013 variation AD.

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46C and to discontinue any product or service per JESD48B. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as “components”) are sold subject to TI’s terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI’s terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers’ products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers’ products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI’s goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or “enhanced plastic” are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have ***not*** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components which meet ISO/TS16949 requirements, mainly for automotive use. Components which have not been so designated are neither designed nor intended for automotive use; and TI will not be responsible for any failure of such components to meet such requirements.

Products		**Applications**	
Audio	www.ti.com/audio	Automotive and Transportation	www.ti.com/automotive
Amplifiers	amplifier.ti.com	Communications and Telecom	www.ti.com/communications
Data Converters	dataconverter.ti.com	Computers and Peripherals	www.ti.com/computers
DLP® Products	www.dlp.com	Consumer Electronics	www.ti.com/consumer-apps
DSP	dsp.ti.com	Energy and Lighting	www.ti.com/energy
Clocks and Timers	www.ti.com/clocks	Industrial	www.ti.com/industrial
Interface	interface.ti.com	Medical	www.ti.com/medical
Logic	logic.ti.com	Security	www.ti.com/security
Power Mgmt	power.ti.com	Space, Avionics and Defense	www.ti.com/space-avionics-defense
Microcontrollers	microcontroller.ti.com	Video and Imaging	www.ti.com/video
RFID	www.ti-rfid.com		
OMAP Mobile Processors	www.ti.com/omap	**TI E2E Community**	e2e.ti.com
Wireless Connectivity	www.ti.com/wirelessconnectivity		

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
Copyright © 2012, Texas Instruments Incorporated